

Bridge Rectifier

EDF1DM

200V / 1A

DATASHEET

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OEM – General Semiconductor

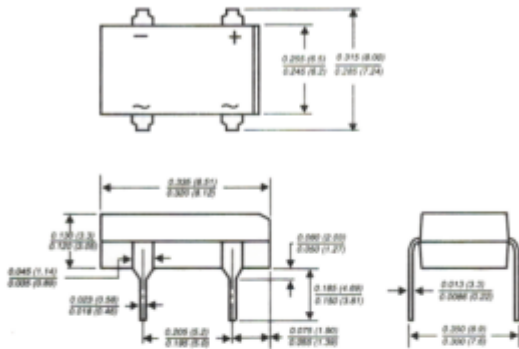
Source: General Semiconductor Databook 1998

EDF1AM THRU EDF1DM

MINIATURE GLASS PASSIVATED FAST EFFICIENT BRIDGE RECTIFIER

Reverse Voltage - 50 to 200 Volts Forward Current - 1.0 Ampere

Case Style DFM



Dimensions in inches and (millimeters)

FEATURES

- ◆ Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- ◆ This series is UL listed under Recognized Component Index, file number E54214
- ◆ Glass passivated chip junctions
- ◆ High forward surge current capability
- ◆ Ideal for printed circuit boards
- ◆ Superfast recovery times for high efficiency
- ◆ High temperature soldering guaranteed:
260°C/10 seconds at 5 lbs. (2.3kg) tension



MECHANICAL DATA

Case: Molded plastic body over passivated junctions

Terminals: Plated leads solderable per MIL-STD-750, Method 2026

Polarity: Polarity symbols marked on body

Mounting Position: Any

Weight: 0.04 ounce, 1.0 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

	SYMBOLS	EDF1AM	EDF1BM	EDF1CM	EDF1DM	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	150	200	Volts
Maximum RMS voltage	V _{RMS}	35	70	106	140	Volts
Maximum DC blocking voltage	V _{DC}	50	100	150	200	Volts
Maximum average forward output rectified current at T _A =40°C	I _(AV)	1.0				Amp
Peak forward surge current single half sine-wave superimposed on rated load (JEDEC Method) T _J =150°C	I _{FSM}	50.0				Amps
Rating for fusing (t < 8.3ms)	I _t	10.0				A ² sec
Maximum instantaneous forward voltage drop per leg at 1.0A	V _F	1.05				Volts
Maximum reverse current at rated DC blocking voltage	I _R	5.0 1.0				μA mA
Maximum reverse recovery time at (NOTE 1)	t _{rr}	50.0				ns
Typical thermal resistance per leg (NOTE 2)	R _{θJA} R _{θJL}	38.0 12.0				°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150				°C

NOTES:

(1) Reverse recovery test conditions: I_F=0.5A, I_R=1.0A, I_{rr}=0.25A

(2) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.51 x 0.51" (13 x 13mm) copper pads

RATINGS AND CHARACTERISTICS CURVES EDF1AM THRU EDF1DM

